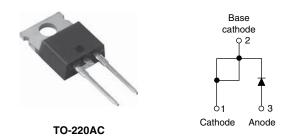
**Vishay Semiconductors** 





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PRODUCT SUMMARY								
Package	TO-220AC							
I <sub>F(AV)</sub>	30 A							
V <sub>R</sub>	600 V							
V <sub>F</sub> at I <sub>F</sub>	1.34 V							
t <sub>rr</sub> (typ.)	23 ns							
T <sub>J</sub> max.	175 °C							
Diode variation	Single die							

#### **FEATURES**

- Reduced Q<sub>rr</sub> and soft recovery
- 175 °C T<sub>J</sub> maximum
- For PFC CRM/CCM operation
- Low forward voltage drop
- Low leakage current
- Designed and qualified according JEDEC<sup>®</sup>-JESD 47



RoHS COMPLIANT

HALOGEN

FREE

to

 Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### **DESCRIPTION / APPLICATIONS**

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS										
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS						
Peak repetitive reverse voltage	V <sub>RRM</sub>		600	V						
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 103 °C	30	٨						
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	200	A						
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C						

<b>ELECTRICAL SPECIFICATIONS</b> ( $T_J = 25$ °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	I <sub>R</sub> = 100 μA	600	-	-					
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 30 A	-	2.0	2.6	V				
		I <sub>F</sub> = 30 A, T <sub>J</sub> = 150 °C	-	1.34	1.75					
Reverse leakage current	I <sub>R</sub>	V <sub>R</sub> = V <sub>R</sub> rated	-	0.3	50					
		$T_J = 150 \ ^{\circ}C, V_R = V_R \text{ rated}$	-	60	500	μA				
Junction capacitance	CT	C <sub>T</sub> V <sub>R</sub> = 600 V		33	-	pF				
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8.0	-	nH				

Revision: 09-Jul-15

Document Number: 94019

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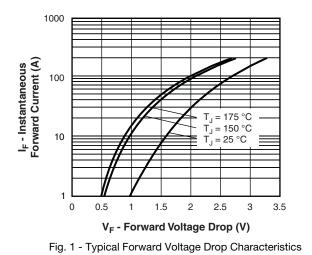
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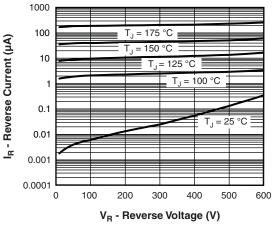
<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25 \ ^{\circ}C$ unless otherwise specified)										
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS			
		$I_F = 1 \text{ A}, \ dI_F/dt = 50$	$I_F = 1 \text{ A}, \text{ d}I_F/\text{d}t = 50 \text{ A}/\mu\text{s}, \text{ V}_R = 30 \text{ V}$		28	35				
Reverse recovery time	t <sub>rr</sub>	$I_F = 1 \text{ A}, \text{ d}I_F/\text{d}t = 10$	-	23	30	ns				
		T <sub>J</sub> = 25 °C		-	31	-	115			
		T <sub>J</sub> = 125 °C	I <sub>F</sub> = 30 A dI <sub>F</sub> /dt = 200 A/µs	-	77	-				
Deels receiver a current	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C		-	3.5	-	٨			
Peak recovery current		T <sub>J</sub> = 125 °C	$V_{\rm R} = 200 \text{ A/}\mu\text{s}$	-	7.7	-	A			
Reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	65	-	nC			
		T <sub>J</sub> = 125 °C		-	345	-				

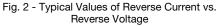
THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	175	°C				
Thermal resistance, junction to case per leg	R <sub>thJC</sub>		-	0.7	1.1					
Thermal resistance, junction to ambient per leg	R <sub>thJA</sub>	Typical socket mount	-	-	70	°C/W				
Thermal resistance, case to heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.2	-					
Weight			-	2.0	-	g				
weight			-	0.07	-	oz.				
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)				
Marking device		Case style TO-220AC	30ETH06							

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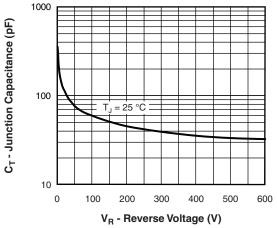


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

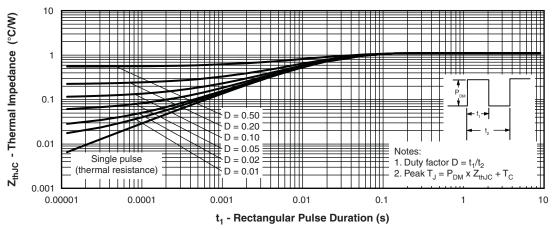
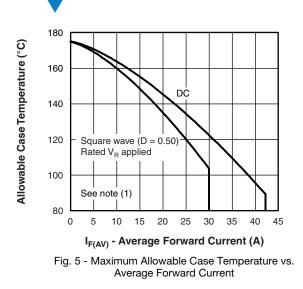


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics

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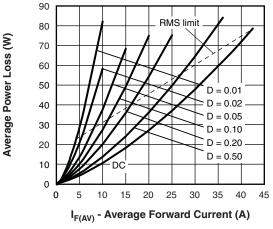
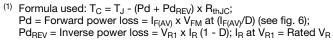


Fig. 6 - Forward Power Loss Characteristics

#### Note



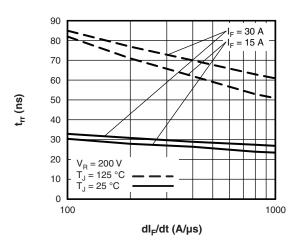
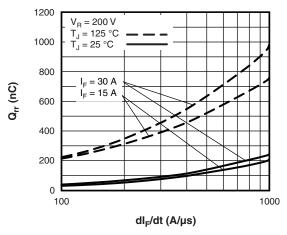


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt





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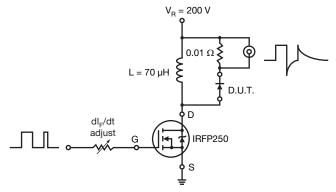
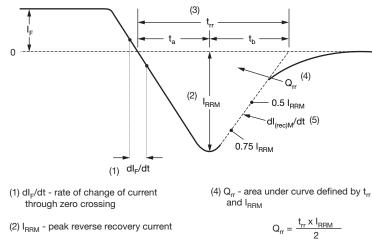


Fig. 9 - Reverse Recovery Parameter Test Circuit



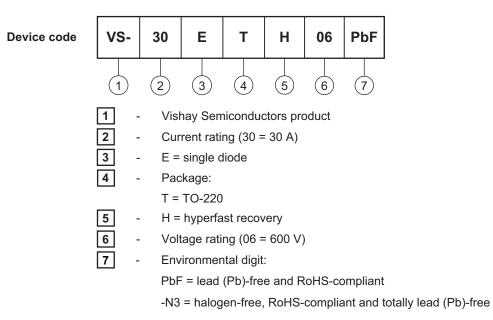
- (3)  $t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through 0.75  $I_{RRM}$  and 0.50  $I_{RRM}$ extrapolated to zero current.
- (5) dI\_{(rec)M}/dt peak rate of change of current during  $t_{\rm b}$  portion of  $t_{\rm rr}$





### **Vishay Semiconductors**

#### **ORDERING INFORMATION TABLE**



ORDERING INFORMATION (Example)									
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION						
VS-30ETH06PbF	50	1000	Antistatic plastic tube						
VS-30ETH06-N3	50	1000	Antistatic plastic tube						

LINKS TO RELATED DOCUMENTS								
Dimensions		www.vishay.com/doc?95221						
Port marking information	TO-220ACPbF	www.vishay.com/doc?95224						
Part marking information	TO-220AC-N3	www.vishay.com/doc?95068						
SPICE model		www.vishay.com/doc?95422						



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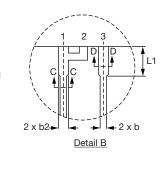
**TO-220AC** 

plane

#### **DIMENSIONS** in millimeters and inches









**Diodes** 1 + 2 - Cathode 3 - Anode

Conforms to JEDEC outline TO-220AC

SYMBOL	MILLIN	IETERS	INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES	
STIVIDOL	MIN.	MAX.	MIN.	MAX.	NOTES	STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	
А	4.25	4.65	0.167	0.183			E1	6.86	8.89	0.270	0.350	6
A1	1.14	1.40	0.045	0.055			E2	-	0.76	-	0.030	7
A2	2.56	2.92	0.101	0.115			е	2.41	2.67	0.095	0.105	
b	0.69	1.01	0.027	0.040			e1	4.88	5.28	0.192	0.208	
b1	0.38	0.97	0.015	0.038	4		H1	6.09	6.48	0.240	0.255	6, 7
b2	1.20	1.73	0.047	0.068			L	13.52	14.02	0.532	0.552	
b3	1.14	1.73	0.045	0.068	4		L1	3.32	3.82	0.131	0.150	2
с	0.36	0.61	0.014	0.024			L3	1.78	2.13	0.070	0.084	
c1	0.36	0.56	0.014	0.022	4		L4	0.76	1.27	0.030	0.050	2
D	14.85	15.25	0.585	0.600	3		ØР	3.54	3.73	0.139	0.147	
D1	8.38	9.02	0.330	0.355			Q	2.60	3.00	0.102	0.118	
D2	11.68	12.88	0.460	0.507	6		θ	90° t	o 93°	90° t	o 93°	
E	10.11	10.51	0.398	0.414	3, 6							

Notes

<sup>(1)</sup> Dimensioning and tolerancing as per ASME Y14.5M-1994

- <sup>(2)</sup> Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- <sup>(4)</sup> Dimension b1, b3 and c1 apply to base metal only
- <sup>(5)</sup> Controlling dimension: inches
- <sup>(6)</sup> Thermal pad contour optional within dimensions E, H1, D2 and E1
- <sup>(7)</sup> Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- <sup>(8)</sup> Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline



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